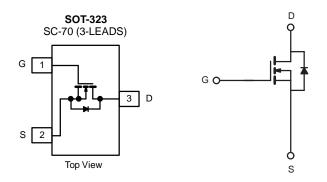


# N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>e</sup>	Q <sub>g</sub> (Typ.)			
	0.0256 at V <sub>GS</sub> = 4.5 V	5 <sup>a</sup>				
20	0.0296 at V <sub>GS</sub> = 2.5 V	5 <sup>a</sup>	8.8 nC			
	0.0345 at V <sub>GS</sub> = 1.8 V	4.2				



#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- DC/DC Converters
- Load Switch for Portable Applications

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		$V_{DS}$	20	V		
Gate-Source Voltage		$V_{GS}$	± 8			
	T <sub>C</sub> = 25 °C		5 <sup>a</sup>	A		
Continuous Drain Current (T. 150 °C)	T <sub>C</sub> = 70 °C	]	4.1			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	4 <sup>b, c</sup>			
	T <sub>A</sub> = 70 °C		3 <sup>b, c</sup>			
Pulsed Drain Current		I <sub>DM</sub>	20	1		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		1.75			
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	l <sub>S</sub>	1.04 <sup>b, c</sup>			
	T <sub>C</sub> = 25 °C		2.1			
Maximum Power Dissination	T <sub>C</sub> = 70 °C	·	1.3	w		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.25 <sup>b, c</sup>	VV		
	T <sub>A</sub> = 70 °C	1	0.8 <sup>b, c</sup>	1		
Operating Junction and Storage Temperature	e Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		
Soldering Recommendations (Peak Tempera	iture)		260			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	80	100	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	40	60	O/ <b>VV</b>		

#### Notes:

- a. Package limited
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 125  $^{\circ}\text{C/W}.$
- e. Based on  $T_C = 25$  °C.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	Cymbol	rest conditions		iyp.	Mux.	Oint
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	20			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			25		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 2.6		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = 250 \mu A$	0.45		1.0	٧
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
<u> </u>		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C			10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α
	(* )	$V_{GS} = 4.5 \text{ V}, I_D = 4.0 \text{ A}$		0.0256		Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 3.7 \text{ A}$		0.0296		
		V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 3.3 A		0.0345		
Forward Transconductance <sup>a</sup>		V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4.0 A		24		S
Dynamic <sup>b</sup>		-		l		
Input Capacitance	C <sub>iss</sub>			865		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		105		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			55		
·		V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 5 V, I <sub>D</sub> = 4.0 A		12	18	
Total Gate Charge	Q <sub>g</sub> Q <sub>gs</sub>			8.8	14	nC
Gate-Source Charge		$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 4.0 \text{ A}$		1.1		
Gate-Drain Charge	$Q_{gd}$			0.7		
Gate Resistance	$R_{g}$	f = 1 MHz	0.5	2.4	4.8	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			8	16	ns
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 2.2 $\Omega$		17	26	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 4$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		31	47	
Fall Time	t <sub>f</sub>			8	16	
Turn-On Delay Time	t <sub>d(on)</sub>			5	10	1
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 2.2 $\Omega$		13	20	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 4 \text{ A}, V_{GEN} = 5 \text{ V}, R_g = 1 \Omega$		21	32	
Fall Time	t <sub>f</sub>			6	12	
Drain-Source Body Diode Characteristic	s			"	l .	
Continuous Source-Drain Diode Current	IS	T <sub>C</sub> = 25 °C			1.75	۸
Pulse Diode Forward Current	I <sub>SM</sub>				20	A
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 4 A, V <sub>GS</sub> = 0 V		0.75	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			12	20	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$	I <sub>F</sub> = 4 A, dI/dt = 100 A/μs, T <sub>J</sub> = 25 °C		5	10	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$i_F - 4 \Lambda$ , $\alpha i / \alpha i = 100 \Lambda / \mu s$ , $i_J = 25 \text{ C}$		7		nc
Reverse Recovery Rise Time	t <sub>b</sub>			5		ns

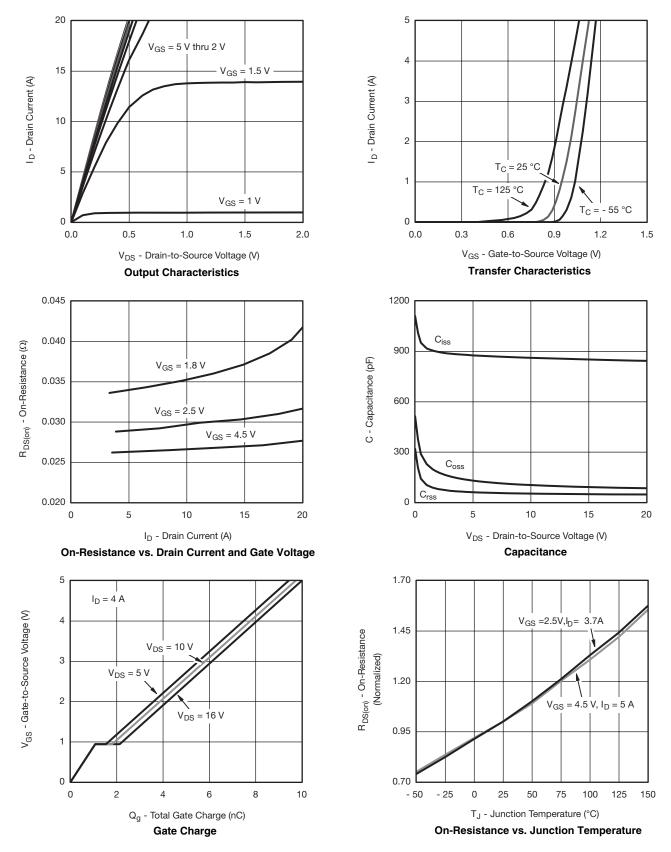
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

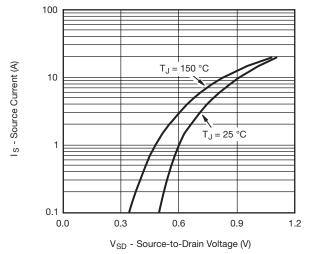


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

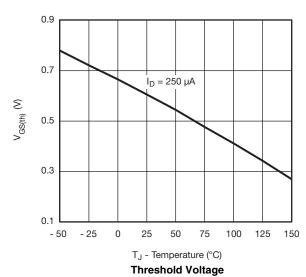


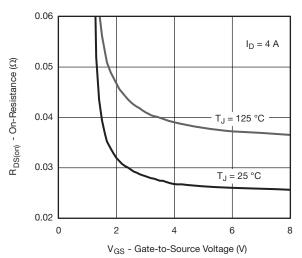


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

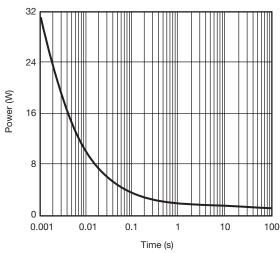


#### Source-Drain Diode Forward Voltage

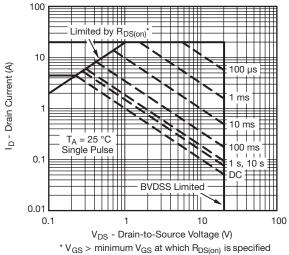




On-Resistance vs. Gate-to-Source Voltage



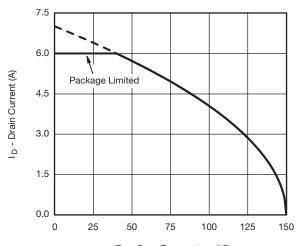
Single Pulse Power (Junction-to-Ambient)



Safe Operating Area, Junction-to-Ambient

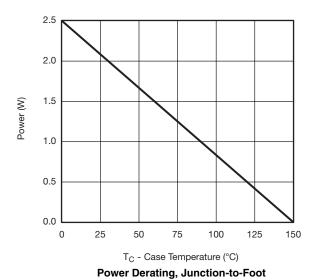


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

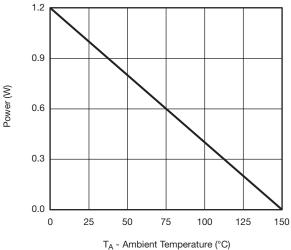


T<sub>C</sub> - Case Temperature (°C)

#### **Current Derating\***







Power Derating, Junction-to-Ambient

 $<sup>^*</sup>$  The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150  $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

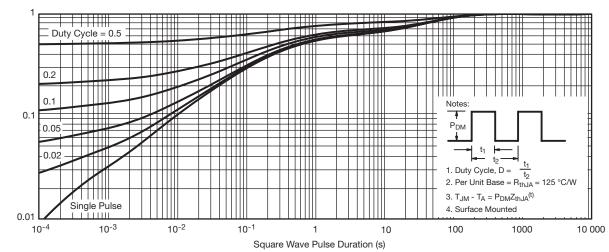
Normalized Effective Transient Thermal Impedance

Normalized Effective Transient Thermal Impedance

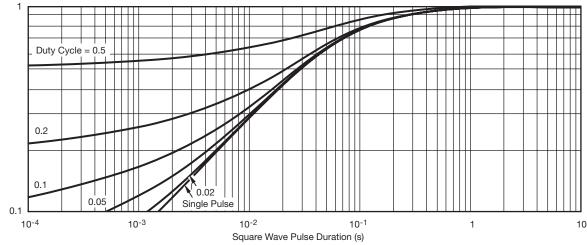
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## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



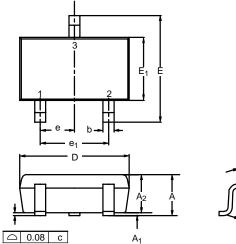
Normalized Thermal Transient Impedance, Junction-to-Ambient

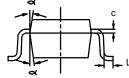


Normalized Thermal Transient Impedance, Junction-to-Foot



## **SC-70: 3-LEADS**



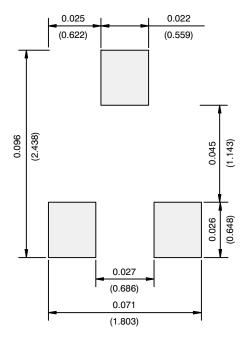


	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	-	0.043
A <sub>1</sub>	_	-	0.10	-	_	0.004
A <sub>2</sub>	0.80	-	1.00	0.031	_	0.039
b	0.25	-	0.40	0.010	_	0.016
С	0.10	-	0.25	0.004	_	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC				0.026BSC	;
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
7	7°Nom				7°Nom	
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549						

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## **RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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